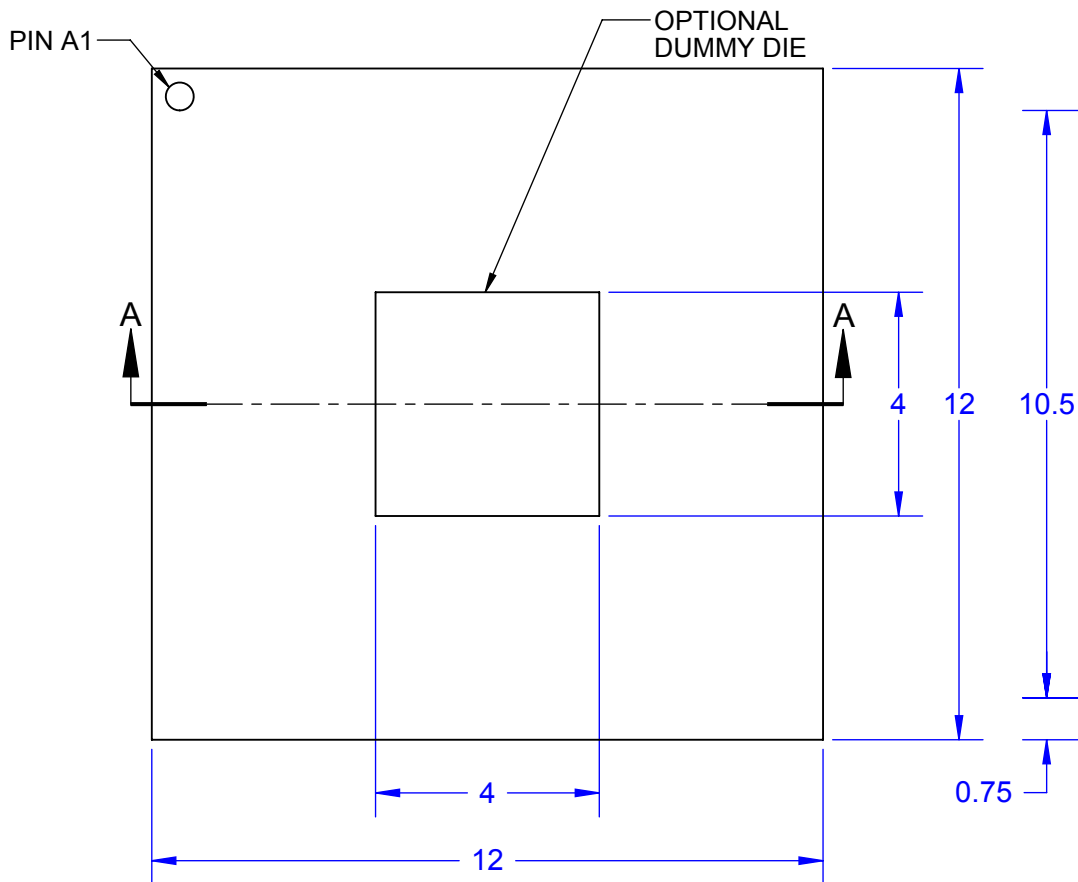
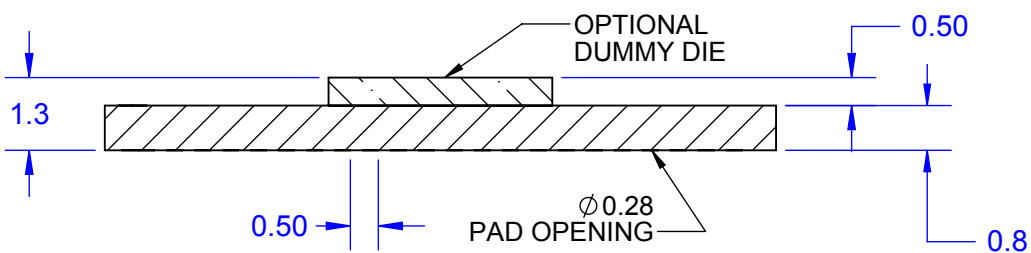
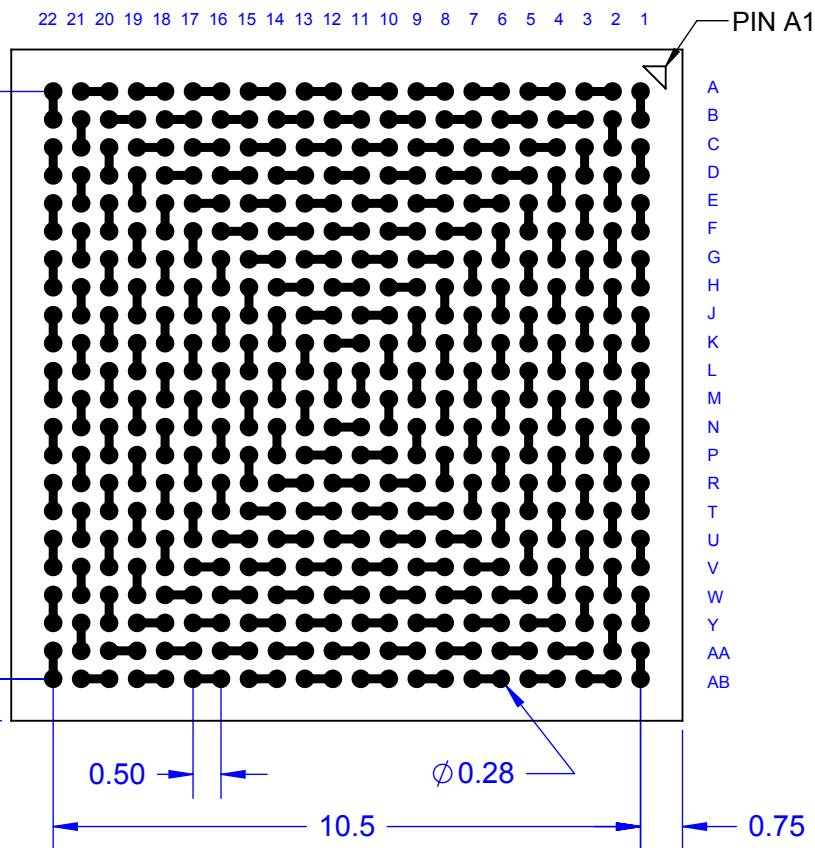


TOP VIEW



BALL VIEW



SECTION A-A

Notes: (Unless Otherwise Specified).

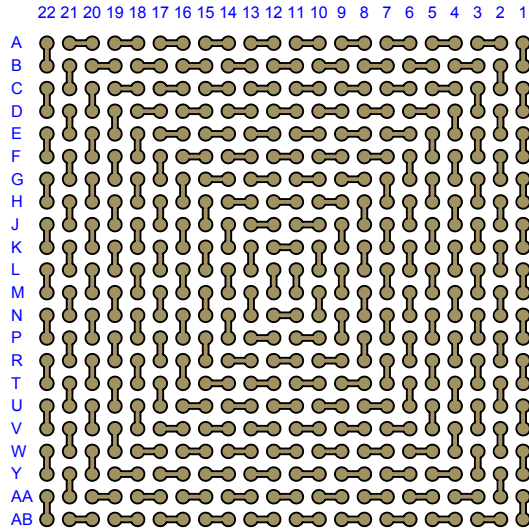
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: NONE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.28mm (11 MIL).
- 5) PAD Cu DIAMETER: 0.355mm (14 MIL).
- 6) SUBSTRATE MATERIAL: FR4.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

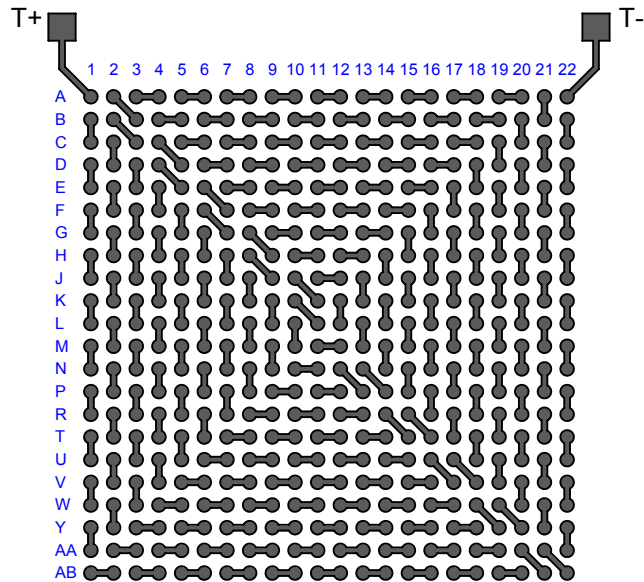
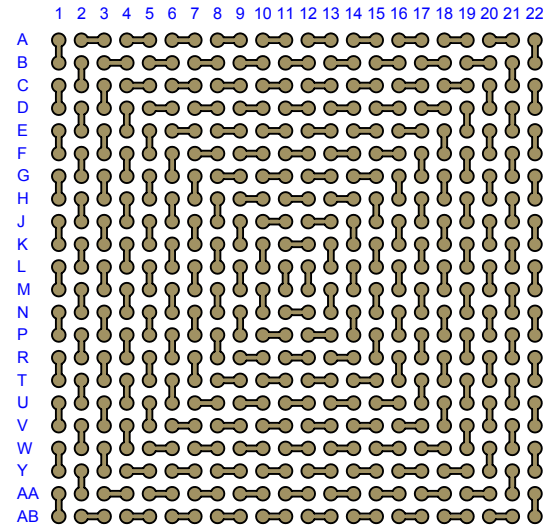
PART NUMBER	PAD	Pb-Free	RoHS	Si DIE
LGA484T.5G-DC229B	Ni/Au	YES	YES	NO
LGA484T.5G-DC229BD	Ni/Au	YES	YES	YES

APPROVALS	DATE	TopLine®		
DRAWN T.Au	07/11/15			
ENG M. Hart	07/11/15	TITLE LGA484T.5G-DC229B DAISY CHAIN DUMMY		
MFG		SCALE 7.5:1	SIZE A	DRAWING NO. 552298
QA				REV A
CUST				
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 3

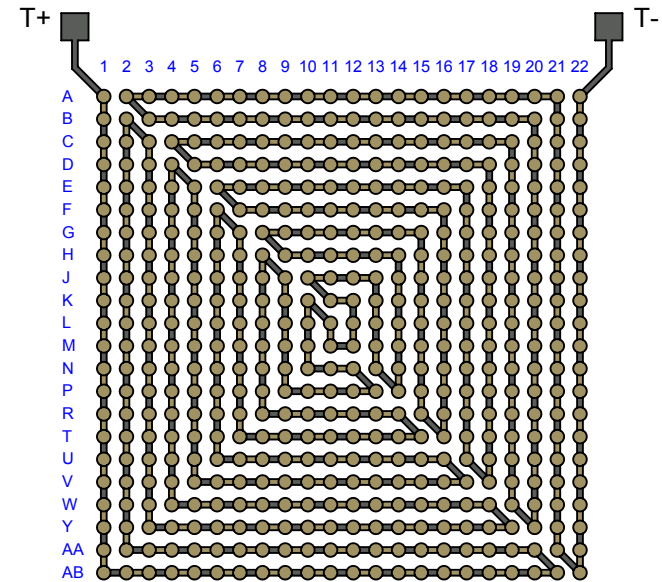
PAD VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



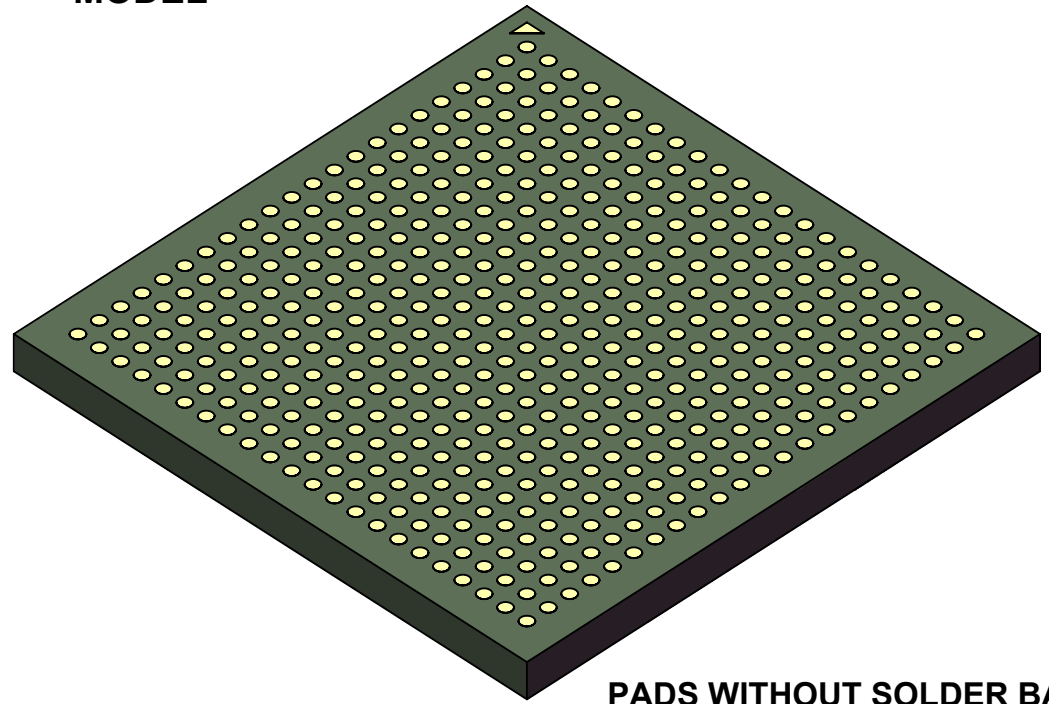
AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (5 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.28mm (11 MIL).

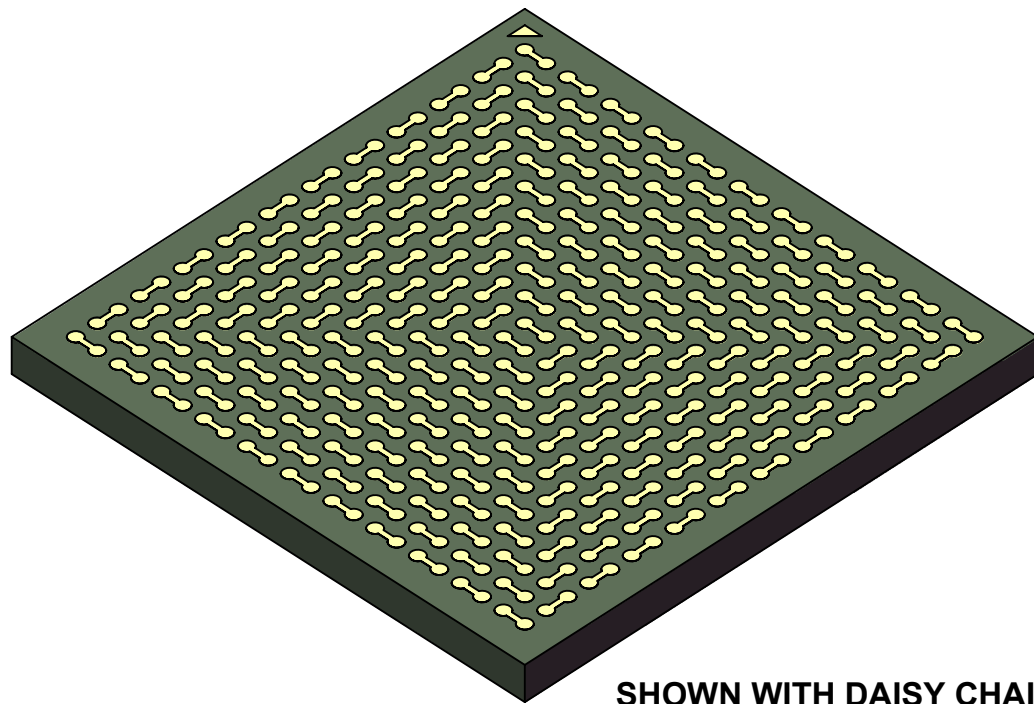
TopLine®			
TITLE		LGA484T.5G-DC229B DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
6:1	A	552298	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL



PADS WITHOUT SOLDER BALLS

**DAISY CHAIN IS UNDER
SOLDER MASK**



SHOWN WITH DAISY CHAIN

TopLine®

TITLE LGA484T.5G-DC229B
DAISY CHAIN DUMMY

SCALE 8:1	SIZE A	DRAWING NO. 552298	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3